

CORRECTED VERSION

(19) World Intellectual Property Organization
International Bureau(43) International Publication Date
20 January 2005 (20.01.2005)

PCT

(10) International Publication Number
WO 2005/006437 A1(51) International Patent Classification⁷: **H01L 23/58**(74) Agent: **VOLMER, Georg**; Philips Intellectual Property
&, Standards GmbH Weissshausstr. 2, 52066 Aachen (DE).(21) International Application Number:
PCT/IB2004/051117(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

(22) International Filing Date: 5 July 2004 (05.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
03102105.8 11 July 2003 (11.07.2003) EP(71) Applicant (for DE only): **PHILIPS INTELLECTUAL
PROPERTY & STANDARDS GMBH** [DE/DE]; Stein-
damm 94, 20099 Hamburg (DE).(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE,
SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
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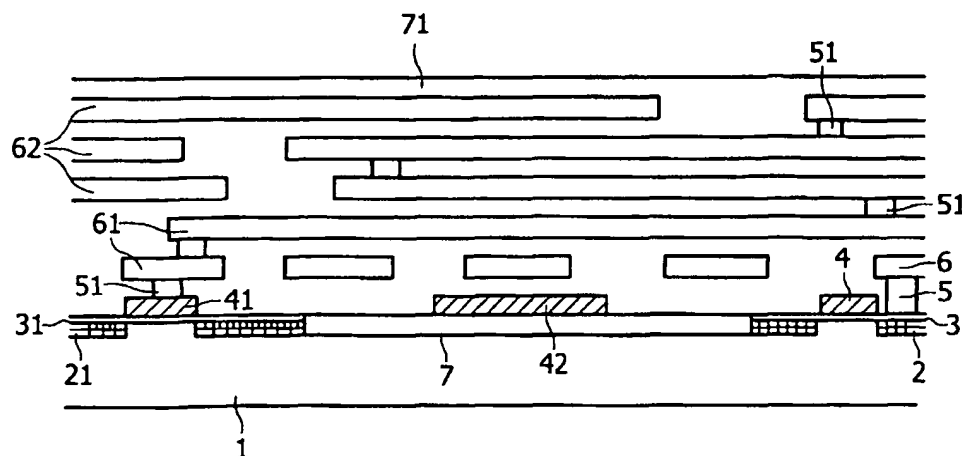
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Published:

— with international search report

[Continued on next page]

(54) Title: SECURITY-SENSITIVE SEMICONDUCTOR PRODUCT, PARTICULARLY A SMART-CARD CHIP



(57) Abstract: To provide a security-sensitive semiconductor product, particularly a smartcard chip, in which are produced not only electrically active structures (2, 3, 4, 5, 6) envisaged by the chip design in the form of circuit functions in and on a wafer (1), which may for example be composed of silicon, but also additional, electrically conductive parts (42, 61, 62) (tiles) of the filling structure, which are insulated from one another, are generated by means of a design program in the remaining residual areas, which greatly impedes, to the reverse engineer the analysis of the security-sensitive circuit structure situated beneath them. The contacts between the parts which are generated, which contacts are for interlinking the latter with the chance signal paths described, may be set "by hand" or by a combination of the design programs in question and a corresponding routing program. The filling conductive parts can also be connected to circuit components, such as transistors, diodes, resistors or capacitors, in order to provide additional circuit functions (e.g. analyzer circuits).

WO 2005/006437 A1



(48) Date of publication of this corrected version:

2 March 2006

(15) Information about Correction:

see PCT Gazette No. 09/2006 of 2 March 2006, Section II

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.